LMH6503 Wideband, Low Power, Linear Variable Gain Amplifier



Literature Number: SNOSA78D



# LMH6503 Wideband, Low Power, Linear Variable Gain Amplifier General Description Features

The LMH<sup>™</sup>6503 is a wideband DC coupled differential input voltage controlled gain stage followed by a high-speed current feedback Op Amp which can directly drive a low impedance load. Gain adjustment range is more than 70dB for up to 10MHz.

Maximum gain is set by external components and the gain can be reduced all the way to cut-off. Power consumption is 370mW with a speed of 135MHz . Output referred DC offset voltage is less than 350mV over the entire gain control voltage range. Device-to-device Gain matching is within 0.7dB at maximum gain. Furthermore, gain at any  $V_{\rm G}$  is tested and the tolerance is guaranteed. The output current feedback Op Amp allows high frequency large signals (Slew Rate = 1800V/µs) and can also drive heavy load current (75mA). Differential inputs allow common mode rejection in low level amplification or in applications where signals are carried over relatively long wires. For single ended operation, the unused input can easily be tied to ground (or to a virtual half-supply in single supply application). Inverting or non-inverting gains could be obtained by choosing one input polarity or the other.

To further increase versatility when used in a single supply application, gain control range is set to be from -1V to +1V relative to pin 11 potential (ground pin). In single supply operation, this ground pin is tied to a "virtual" half supply. Gain control pin has high input impedance to simplify its drive requirement. Gain control is linear in V/V throughout the gain adjustment range. Maximum gain can be set to be anywhere between 1V/V to 100V/V or higher. For linear in dB gain control applications, see LMH6502 datasheet.

The LMH6503 is available in the SOIC-14 and TSSOP-14 package.



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 $V_{\rm S} = \pm 5V$ ,  $T_{\rm A} = 25^{\circ}$ C,  $R_{\rm F} = 1$ k $\Omega$ ,  $R_{\rm G} = 174\Omega$ ,  $R_{\rm L} = 100\Omega$ ,  $A_{\rm V} = 10$ 

- =  $A_{V(MAX)}$  = 10, Typical values unless specified. -3dB BW 135MHz Gain control BW 100MHz Adjustment range (typical over temp) 70dB Gain matching (limit) ±0.7dB 1800V/µs Slew rate Supply current (no load) 37mA Linear output current ±75mA • Output voltage ( $R_1 = 100\Omega$ ) ±3.2V Input voltage noise 6.6nV/ √Hz Input current noise 2.4pA/ √Hz THD (20MHz,  $R_L = 100\Omega$ ,  $V_O = 2V_{PP}$ ) -57dBc Replacement for CLC522
- **Applications**
- Variable attenuator
- AGC
- Voltage controller filter
- Multiplier



### Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

ESD Tolerance: (Note 4)	
Human Body	2KV
Machine Model	200V
Input Current	±10mA
V <sub>IN</sub> Differential	$\pm (V^+ - V^-)$
Output Current	120mA (Note 3)
Supply Voltages (V <sup>+</sup> - V <sup>-</sup> )	12.6V
Voltage at Input/ Output pins	V+ +0.8V,V 0.8V
Soldering Information:	

Infrared or Convection (20 sec)	235°C
Wave Soldering (10 sec)	260°C
Storage Temperature Range	–65°C to +150°C
Junction Temperature	+150°C

## Operating Ratings (Note 1)

Supply Voltages (V <sup>+</sup> - V <sup>-</sup> )		5V to 12V
Temperature Range		–40°C to +85°C
Thermal Resistance:	$\theta_{JA}$	$\theta_{\rm JC}$
14-Pin SOIC	138°C/W	45°C/W
14-Pin TSSOP	160°C/W	51°C/W

### Electrical Characteristics(Note 2)

Unless otherwise specified, all limits guaranteed for  $T_J = 25^{\circ}C$ ,  $V_S = \pm 5V$ ,  $A_{V(MAX)} = 10$ ,  $V_{CM} = 0V$ ,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ ,  $V_{IN^-}$ \_DIFF = ±0.1V,  $R_L = 100\Omega$ ,  $V_G = +1V$ . **Boldface** limits apply at the temperature extremes.

Symbol	Parameter	Conditions	Min (Note 6)	Typ (Note 6)	Max (Note 6)	Units	
,	<sup>7</sup> Domain Response		(	(	(	•	
BW	-3dB Bandwidth	V <sub>OUT</sub> < 0.5 <sub>PP</sub>		135			
		$V_{OUT} < 0.5_{PP}, A_{V(MAX)} = 100$		50		MHz	
GF	Gain Flatness	$V_{OUT} < 0.5V_{PP},$ -1V < V <sub>G</sub> < 1V, ±0.2dB		40		MHz	
Att Range	Flat Band (Relative to Max Gain)	±0.2dB Flatness, f < 30MHZ		20			
	Attenuation Range (Note 13)	±0.1dB, f < 30MHZ		6.6		MHz	
BW Control	Gain Control Bandwidth	V <sub>G</sub> = 0V (Note 11)		100		MHz	
PL	Linear Phase Deviation	DC to 60MHz		1.6		deg	
G Delay	Group Delay	DC to 130MHz		2.6		ns	
CT (dB)	Feed-through	$V_G = -1.2V$ , 30MHz (Output Referred)		-48		dB	
GR Gain Adjustment Range		f < 10MHz		79			
		f < 30MHz		68		dB	
Time Dom	ain Response						
t <sub>r</sub> , t <sub>f</sub>	Rise and Fall Time	0.5V Step		2.2		ns	
OS%	Overshoot	0.5V Step		10		%	
SR Slew Rate		4V Step (Note 5)		1800		V/µs	
△G Rate Gain Change Rate		$V_{IN} = 0.3V$ , 10%–90% of final output		4.6		dB/ns	
Distortion	& Noise performance	1					
HD2	2 <sup>nd</sup> Harmonic Distortion	2V <sub>PP</sub> , 20MHz		-60		dBc	
HD3 3 <sup>rd</sup> Harmonic Distortion		2V <sub>PP</sub> , 20MHz		-61		dBc	
THD	Total Harmonic Distortion	2V <sub>PP</sub> , 20MHz		-57		dBc	
En tot Total Equivalent Input Noise		1MHz to 150MHz		6.6		nV/√Hz	
Input Noise Current		1MHz to 150MHz		2.4		pA/ √Hz	
DG Differential Gain		f = 4.43MHz, $R_L$ = 150 $\Omega$ , Neg. Sync		0.15		%	
DP	Differential Phase	f = 4.43MHz, $R_L$ = 150 $\Omega$ , Neg. Sync		0.22		deg	

0	Describer		Min	Тур	Max	
Symbol	Parameter cellaneous Performance	Conditions	(Note 6)	(Note 6)	(Note 6)	Units
GACCU	Gain Accuracy (see Application	V -1 0V		+0.25	+0.9/-0.4	
GACCU	Notes)	$V_{\rm G} = 1.0V$ $0V < V_{\rm G} < 1V$		+0.25 ±0.3		dD
		$-0.7V < V_G < 1V$		±0.3 ±0.4	+1.3/-1.5 +4.4/-4.3	dB
G Match	Coin Matching (and Application	-		±0.4	±0.7	
G Match	Gain Matching (see Application Notes)	$V_{\rm G} = 1.0$		_		dD
	(Notes)	$0 < V_G < 1V$		_	+1.7/-1.1	dB
		$-0.7V < V_{\rm G} < 1V$	1.50	-	+4.0/-4.7	
К	Gain Multiplier (see Application Notes)		1.58 <b>1.58</b>	1.72	1.87 <b>1.91</b>	V/V
V	Input Voltage Range	Pin 3 & 6 Common Mode,	±2.0	±2.2	1.91	V
V <sub>CM</sub>		CMRR  > 50dB (Note 9)	±2.0 ±1.80	±2.2		v
V	Differential Input Voltage	Across pins 3 & 6	±0.34	±0.37		
$V_{IN\_DIFF}$		Across pins 5 & 6	±0.34 ±0.28	±0.37		V
	R <sub>G</sub> Current	Pins 4 & 5	±1.70	±2.30		mA
I <sub>RG MAX</sub>	Ing Ourient		±1.60	±2.00		
IBIAS	Bias Current	Pins 3 & 6 (Note 7)		11	18	
BIAS					20	
		Pins 3 & 6 (Note 7),		3	10	μA
		$V_{s} = \pm 2.5V$			13	
TC <sub>BIAS</sub>	Bias Current Drift	Pin 3 & 6 (Note 8)		100		nA/°C
I <sub>OFF</sub>	Offset Current	Pin 3 & 6		0.01	2.0	
· OFF					2.5	μA
TC I <sub>OFF</sub>	Offset Current Drift	(Note 8)		5		nA/°C
R <sub>IN</sub>	Input Resistance	Pin 3 & 6		750		kΩ
C <sub>IN</sub>	Input Capacitance	Pin 3 & 6		5		pF
IV <sub>G</sub>	V <sub>G</sub> Bias Current	Pin 2, $V_{G} = 1.4V(Note 7)$		45		μA
TC IV <sub>G</sub>	V <sub>G</sub> Bias Drift	Pin 2 (Note 8)		20		nA/°C
R V <sub>G</sub>	V <sub>G</sub> Input Resistance	Pin 2		70		KΩ
C V <sub>G</sub>	V <sub>G</sub> Input Capacitance	Pin 2		1.3		pF
V <sub>OUT</sub>	Output Voltage Range	$R_{\rm L} = 100\Omega$	±3.00	±3.20		
•001			±2.97	_0.20		
		R <sub>I</sub> Open	±3.95	±4.05		V
			±3.90			
R <sub>OUT</sub>	Output Impedance	DC		0.1		Ω
I <sub>OUT</sub>	Output Current	V <sub>OUT</sub> ±4V from Rails	±75	±90		mA
001			±70			
Vo	Output Offset Voltage	$-1V < V_{G} < 1V$		±80	±350	mV
OFFSET					±380	
+PSRR	+Power Supply Rejection Ratio	Input Referred, 1V change,		-80	-58	dB
	(see (Note 10))	V <sub>G</sub> = 1.4V			-56	
-PSRR	-Power Supply Rejection Ratio	Input Referred, 1V change,		-67	-57	dB
	(see (Note 10))	$V_{G} = 1.4V$			-51	
CMRR	Common Mode Rejection Ratio	Input Referred, V <sub>G</sub> = 1V		-67		dB
	(see (Note 9))	$-1.8V < V_{CM} < 1.8V$				
Is	Supply Current	R <sub>L</sub> = Open		37	50	
					53	mA
		$R_L = Open, V_S = \pm 2.5V$		12	20	11174
					23	

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LMH6503

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### Electrical Characteristics(Note 2) (Continued)

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications, see the Electrical Characteristics tables.

**Note 2:** Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that  $T_J = T_A$ . No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where  $T_J > T_A$ . **Note 3:** The maximum output current ( $I_{OUT}$ ) is determined by device power dissipation limitations or value specified, whichever is lower.

Note 4: Human body model:  $1.5k\Omega$  in series with 100pF. Machine model:  $0\Omega$  in series with 200pF.

Note 5: Slew Rate is the average of the rising and falling rates.

Note 6: Typical values represent the most likely parametric norm. Bold numbers refer to over temperature limits.

Note 7: Positive current correspondes to current flowing in the device.

Note 8: Drift determined by dividing the change in parameter distribution at temperature extremes by the total temperature change.

Note 9: CMRR definition:  $[|\Delta V_{OUT}/\Delta V_{CM}|/A_V]$  with 0.1V differential input voltage.  $\Delta V_{OUT}$  is the change in output voltage with offset shift subtracted out.

Note 10: +PSRR definition:  $[|\Delta V_{OUT}/\Delta V^+| /A_V]$ , -PSRR definition:  $[|\Delta V_{OUT}/\Delta V^-| /A_V]$  with 0.1V differential input voltage.  $\Delta V_{OUT}$  is the change in output voltage with offset shift subtracted out.

Note 11: Gain Control Frequency Response Schematic:



Note 12: Gain/Phase normalized to low frequency value at each A<sub>V</sub>.

Note 13: Flat Band Attenuation (Relative To Max Gain) Range Definition: Specified as the attenuation range from maximum which allows gain flatness specified (either ±0.2dB or ±0.1dB), relative to A<sub>VMAX</sub> gain. For example, for f<30MHz, here are the Flat Band Attenuation ranges:

±0.2dB: 10V/V down to 1V/V=20dB range

±0.1dB: 10V/V down to 4.7V/V=6.5dB range

### Connection Diagram



### **Ordering Information**

Package	Part Number	Package Marking	Transport Media	NSC Drawing	
14-pin SOIC	LMH6503MA	LMH6503MA	LMH6503MA 55 Units/Rail		
	LMH6503MAX	2.5k Units Tape and Reel			
14-Pin TSSOP	hin TSSOP		MTC14		
14-PIII 1550P	LMH6503MTX		2.5k Units Tape and Reel	1 1011014	

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Typical Performance Charateristics Unless otherwise specified: V<sub>S</sub> = ±5V, 25°C, V<sub>G</sub> = V<sub>G\_MAX</sub>, V<sub>CM</sub> = 0V,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)





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50M

f (10 MHz/DIV)





Frequency Response for Various  $V_G$  (A<sub>VMAX</sub> = 100) (Large Signal)





Frequency Response for Various  $V_G$  (A<sub>VMAX</sub> = 100) (Small Signal)

**Typical Performance Charateristics** Unless otherwise specified:  $V_s = \pm 5V$ , 25°C,  $V_G = V_{G_MAX}$ ,  $V_{CM} = 0V$ ,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)





Typical Performance Charateristics Unless otherwise specified: V<sub>S</sub> = ±5V, 25°C, V<sub>G</sub> = V<sub>G\_MAX</sub>, V<sub>CM</sub> = 0V,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)









**Typical Performance Charateristics** Unless otherwise specified:  $V_S = \pm 5V$ , 25°C,  $V_G = V_{G_MAX}$ ,  $V_{CM} = 0V$ ,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)

#### Output Offset Voltage vs.V<sub>CM</sub> (Typical Unit 3)



Gain Flatness and Linear Phase Deviation



Group Delay vs. Frequency







Gain Flatness Frequency vs. Gain (Note 13)







Typical Performance Charateristics Unless otherwise specified: V<sub>S</sub> = ±5V, 25°C, V<sub>G</sub> = V<sub>G\_MAX</sub>, V<sub>CM</sub> = 0V,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)

### Gain vs. V<sub>G</sub> Including Limits







Output Offset Voltage vs. V<sub>G</sub> (Typical Unit 2)





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Output Offset Voltage vs. V<sub>G</sub> (Typical Unit 1)



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**Typical Performance Charateristics** Unless otherwise specified:  $V_S = \pm 5V$ , 25°C,  $V_G = V_{G_MAX}$ ,  $V_{CM} = 0V$ ,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)







Noise vs. Frequency  $(A_{VMAX} = 2)$ 



Output Offset Voltage vs. ±V<sub>s</sub> for Various V<sub>G</sub> (Typical Unit 2)



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Gain vs.  $V_G$  (±2.5V)



= 10



Typical Performance Charateristics Unless otherwise specified: V<sub>S</sub> = ±5V, 25°C, V<sub>G</sub> = V<sub>G\_MAX</sub>, V<sub>CM</sub> = 0V,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)



2

1.5

1 0.5

0

0

20

40

60

I<sub>OUT</sub> (mA)

80

100





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20

15

50

45

40

-10

A<sub>VMAX</sub> = 10

 $V_{G} = V_{GMAX}$ 

-5

0

5

P<sub>OUT</sub> (dBm)

10

**Typical Performance Charateristics** Unless otherwise specified:  $V_S = \pm 5V$ , 25°C,  $V_G = V_{G_MAX}$ ,  $V_{CM} = 0V$ ,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)



**Typical Performance Charateristics** Unless otherwise specified:  $V_S = \pm 5V$ , 25°C,  $V_G = V_{G_MAX}$ ,  $V_{CM} = 0V$ ,  $R_F = 1k\Omega$ ,  $R_G = 174\Omega$ , both inputs terminated in 50 $\Omega$ ,  $R_L = 100\Omega$ , Typical values, results referred to device output: (Continued)



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### **Application Information**

#### THEORY OF OPERATION

The LMH6503 is a linear wideband variable-gain amplifier as illustrated in Figure 1. A voltage input signal may be applied differentially between the two inputs (+V<sub>IN</sub>, -V<sub>IN</sub>), or singleendedly by grounding one of the two unused inputs. The LMH6503 input buffers convert the input voltage to a current  $(I_{BG})$  that is a function of the differential input voltage (V<sub>INPUT</sub> =  $(+V_{IN}) - (-V_{IN})$  and the value of the gain setting resistor  $(R_G)$ . This current  $(I_{RG})$  is then mirrored to a gain stage with a current gain of K (1.72 nominal). The voltage controlled two-quadrant multiplier attenuates this current which is then converted to a voltage via the output amplifier. This output amplifier is a current feedback op amp configured as a Transimpedance amplifier. Its Transimpedance gain is the feedback resistor (R<sub>F</sub>). The input signal, output, and gain control are all voltages. The output voltage can easily be calculated as shown in Equation 1:

$$V_{OUT} = I_{RG} \times K \times \left[\frac{V_{G} + 1}{2}\right] \times R_{F} \text{ FOR -1 } < V_{G} < +1$$
(1)

Where K = 1.72 (Nominal) since:

$$I_{RG} = \frac{V_{INPUT}}{R_G}$$

The gain of the LMH6503 is therefore a function of three external variables:  $R_G$ ,  $R_F$ , and  $V_G$  as expressed in Equation 2:

$$A_{V} = \frac{R_{F}}{R_{G}} \times 1.72 \times \left[\frac{V_{G}+1}{2}\right]$$

The gain control voltage (V<sub>G</sub>) has an ideal input range of  $-1V < V_G < +1V$ . At V<sub>G</sub> = +1V, the gain of the LMH6503 is at its maximum as expressed in Equation 3:

$$A_V = 1.72 \frac{R_F}{R_G}$$

(3)

Notice also that Equation 3 holds for both differential and single ended operation.



FIGURE 1. LMH6503 Functional Block Diagram

#### CHOOSING R<sub>F</sub> AND R<sub>G</sub>

 $R_{\rm G}$  is calculated from Equation 4.  $V_{\rm INPUTMAX}$  is the maximum peak

$$R_{G} = \frac{V_{INPUT_{MAX}}}{I_{R_{GMAX}}}$$
(4)

input voltage (V<sub>pk</sub>) determined by the application. I<sub>RGMAX</sub> is the maximum allowable current through R<sub>G</sub> and is typically 2.3mA. Once A<sub>VMAX</sub> is determined from the minimum input and desired output voltages, R<sub>F</sub> is then determined using Equation 5. These values of R<sub>F</sub> and R<sub>G</sub> are

(2)

### Application Information (Continued)

$$R_{F} = \frac{1}{K} * R_{G} * A_{VMAX}$$

the minimum possible values that meet the input voltage and maximum gain constraints. Scaling the resistor values will decrease bandwidth and improve stability.

Figure 2 illustrates the resulting LMH6503 bandwidths as a function of the maximum ( y axis) and minimum (related to x axis) input voltages when  $V_{OUT}$  is held constant at  $1V_{PP}$ .



FIGURE 2. Bandwidth vs. VINMAX and AVMAX

#### **ADJUSTING OFFSETS**

Treating the offsets introduced by the input and output stages of the LMH6503 is accomplished with a two step process. The offset voltage of the output stage is treated by first applying -1.1V on V<sub>G</sub>, which effectively isolates the input stage and multiplier core from the output stage. As illustrated in *Figure 3*, the trim pot located at R14 on the LMH6503 Evaluation Board (CLC730033) should then be adjusted in order to null the offset voltage seen at the LMH6503's output (pin 10).



FIGURE 3. Nulling the Output Offset Voltage

Once this is accomplished, the offset errors introduced by the input stage and multiplier core can then be treated. The second step requires the absence of an input signal and matched source impedances on the two input pins in order to cancel the bias current errors. This done, then +1.1V should be applied to V<sub>G</sub> and the trim pot located at R<sub>10</sub> adjusted in order to null the offset voltage seen at the LMH6503's output. If a more limited gain range is anticipated, the above adjustments should be made at these operating points. These steps will minimize the output offset voltage. However, since the offset term itself varies with the gain setting, the correction is not perfect and some residual output offset will remain.

#### GAIN ACCURACY

(5)

Defined as the ratio of measured gain (V/V), at a certain V<sub>G</sub>, to the best fit line drawn through the typical gain (V/V) distribution for  $-1V < V_G < 1V$  (results expressed in dB) (See *Figure 4*). The best fit gain (A<sub>V</sub>) is given by:

$$A_V (V/V) = 4.87 V_G + 4.61 \mbox{(6)} \label{eq:result}$$
 For: -1V  $\leq V_G \leq$  + 1V,  $R_F$  = 1k\Omega,  $R_G$  = 174 $\Omega$ 

For a  $V_{\rm G}$  range, the value specified in the tables represents the worst case accuracy over the entire range. The "Typical" value would be the worst case ratio between the "Typical Gain" and the best fit line. The "Max" value would be the worst case between the max/min gain limit and the best fit line.

#### GAIN MATCHING

Defined as the limit on gain variation at a certain  $V_G$  (expressed in dB) (See *Figure 4*). Specified as "Max" only (no "Typical"). For a  $V_G$  range, the value specified represents the worst case matching over the entire range. The "Max" value would be the worst case ratio between the max/min gain limit and the typical gain.



# Application Information (Continued)

#### NOISE

*Figure 5* describes the LMH6503's output-referred spot noise density as a function of frequency with A<sub>VMAX</sub> = 10V/V. The plot includes all the noise contributing terms. However, with both inputs terminated in 50 $\Omega$ , the input noise contribution is minimal. At A<sub>VMAX</sub> = 10V/V, the LMH6503 has a typical flat-band input-referred spot noise density (e<sub>in</sub>) of 6.6nV/  $\sqrt{Hz}$ . For applications with –3dB BW extending well into the flat-band region, the input RMS voltage noise can be determined from the following single-pole model:

$$V_{RMS} = e_{in} * \sqrt{1.57 * (-3dB BANDWIDTH)}$$

(7)



FIGURE 5. Output Referred Voltage Noise vs. Frequency

#### CIRCUIT LAYOUT CONSIDERATIONS

Good high-frequency operation requires all of the decoupling capacitors shown in *Figure 6* to be placed as close as possible to the power supply pins in order to insure a proper high-frequency low-impedance bypass. Adequate ground plane and low inductive power returns are also



FIGURE 6. Required Power Supply Decoupling

required of the layout. Minimizing the parasitic capacitances at pins 3, 4, 5, 6, 9, 10 and 12 will assure best high frequency performance. The parasitic inductance of component leads or traces to pins 4, 5 and 9 should also be kept to a minimum. Parasitic or load capacitance,  $C_L$ , on the output (pin 10) degrades phase margin and can lead to frequency response peaking or circuit oscillation. The LMH6503 is fully stable when driving a 100 $\Omega$  load. With reduced load (e.g. 1k $\Omega$ ) there is a possibility of instability at very high frequencies beyond 400MHz especially with a capacitive load. When the LMH6503 is connected to a light load as such, it is recommended to add a snubber network to the output (e.g. 100 $\Omega$  and 39pF in series tied between the LMH6503 output and ground).  $C_L$  can also be isolated from the output (pin 10).

Component parasitics also influence high frequency results. Therefore it is recommended to use metal film resistors such as RN55D or leadless components such as surface mount devices. High profile sockets are not recommended.

National Semiconductor suggests the following evaluation board as a guide for high frequency layout and as an aid in device testing and characterization:

Device	Package	Evaluation Board Part Number
LMH6503MA	SOIC-14	CLC730033
LMH6503MT	TSSOP-14	CLC730146

The evaluation board is shipped when a device sample request is placed with National Semiconductor.

#### SINGLE SUPPLY OPERATION

It is possible to operate the LMH6503 with a single supply. To do so, tie pin 11 (GND) to a potential about mid point between V<sup>+</sup> and V<sup>-</sup>. Two examples are shown in *Figure 7* & *Figure 8*.



FIGURE 7. AC Coupled Single Supply VGA

### Application Information (Continued)



FIGURE 8. Transformer Coupled Single Supply VGA

#### **OPERATING AT LOWER SUPPLY VOLTAGES**

The LMH6503 is rated for operation down to 5V supplies (V<sup>+</sup> - V<sup>-</sup>). There are some specifications shown for operation at ±2.5V within the data sheet (i.e. Frequency Response, CMRR, PSRR, Gain vs. V<sub>G</sub>, etc.). Compared to ±5V operation, at lower supplies:

a) V<sub>G</sub> range constricts. Referring to *Figure 9*, note that  $V_{G\_MAX}$  (V<sub>G</sub> voltage required to get maximum gain) is 0.5V (V<sub>S</sub> = ±2.5V) compared to 1.0V for V<sub>S</sub> = ±5V. At the same time, gain cut-off (V<sub>G\_MIN</sub>) would shift to -0.5V from - 1V with V<sub>S</sub> = ±5V.

Table 1 shows the approximate expressions for various  $V_{\rm G}$  voltages as a function of V^:

V <sub>G</sub>	Definition	Expression (V)
V <sub>G_MIN</sub>	Gain Cut-off	0.2 x V <sup>-</sup>
V <sub>G_MID</sub>	A <sub>VMAX</sub> /2	0
V <sub>G_MAX</sub>	A <sub>VMAX</sub>	-0.2 x V <sup>-</sup>

Table 1: V<sub>G</sub> Definition Based on V<sup>-</sup>

b)  $V_{G\_LIMIT}$  (maximum permissible voltage on  $V_G$ ) is reduced. This is due to limitations within the device arising from transistor headroom. Beyond this limit, device performance will be affected (non-destructive). Referring to *Figure 9*, note that with V<sup>+</sup> = 2.5V, and V<sup>-</sup> = -4V, V\_{G\\_LIMIT} is approaching  $V_{G\_MAX}$  and already "Max gain" is reduced by 1dB. This means that operating under these conditions has reduced the maximum permissible voltage on  $V_G$  to a level below what is needed to get Max gain. If supply voltages are asymmetrical, reference *Figure 9* and

Figure 10 plots to make sure the region of operation is not overly restricted by the "pinching" of  $V_{G\_LIMIT},$  and  $V_{G^-}\__{MAX}$  curves.

c) "Max\_gain" reduces. There is an intrinsic reduction in max gain when the total supply voltage is reduced (see Typical Performance Characteristics plots for Gain vs.  $V_{\rm G}$  ( $V_{\rm S}$  = ±2.5V). In addition, there is the more drastic mechanism described in "b" above and shown in *Figure 9*.

Similar plots for  $V^+ = 5V$  operation are shown in *Figure 10* for comparison and reference.



FIGURE 9.  $V_{G\_MAX}$ ,  $V_{G\_LIMIT}$ , & Max-gain vs. V<sup>-</sup> (V<sup>+</sup> = 2.5V)



FIGURE 10.  $V_{G_{MAX}}$ ,  $V_{G_{LIMIT}}$ , & Max-gain vs.  $V^{-}$ ( $V^{+} = 5V$ )

## **Application Circuits**

### FOUR-QUADRANT MULTIPLIER

Applications requiring multiplication, squaring or other nonlinear functions can be implemented with four-quadrant multipliers. The LMH6503 implements a four-quadrant multiplier as illustrated in *Figure 11*:



FIGURE 11. Four Quadrant Multiplier

#### FREQUENCY SHAPING

Frequency shaping and bandwidth extension of the LMH6503 can be accomplished using parallel networks connected across the  $R_{\rm G}$  ports. The network shown in the *Figure 12* schematic will effectively extend the LMH6503's bandwidth.



FIGURE 12. Frequency Shaping

#### 2<sup>nd</sup> ORDER TUNABLE BANDPASS FILTER

The LMH6503 Variable-Gain Amplifier placed into a feedback loop provides signal processing function such as in a 2nd order tunable bandpass filter. The center frequency of the 2nd order bandpass shown in *Figure 13* is adjusted through the use of the LMH6503's gain control voltage,  $V_{G}$ . The integrators implemented with two sections of a LMH6682, provide the coefficients for the transfer function.







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#### FIGURE 13. Tunable Bandpass Filter



### Notes

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